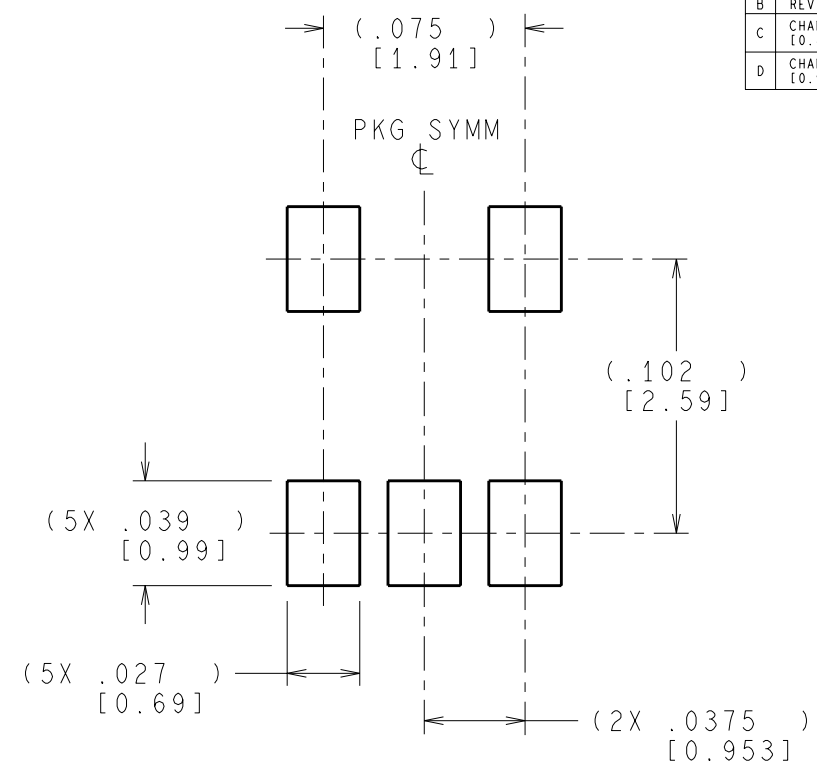
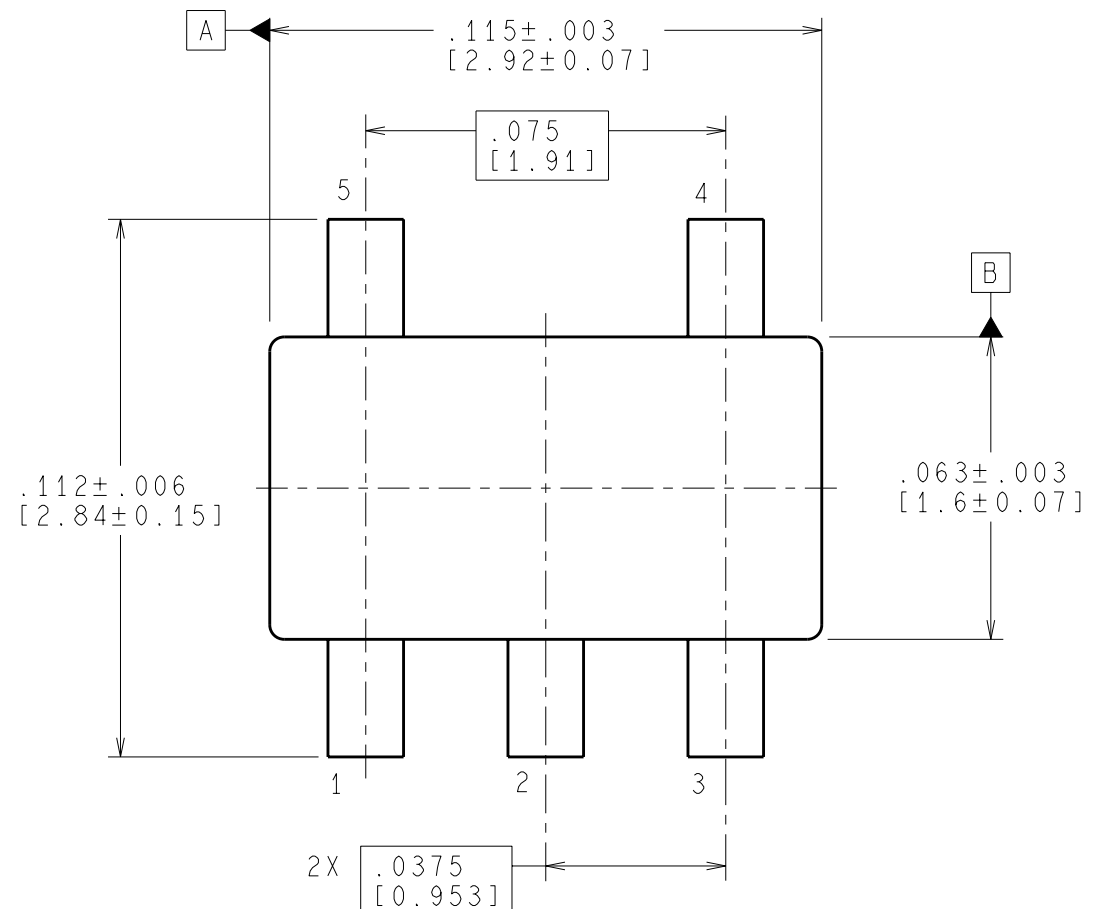
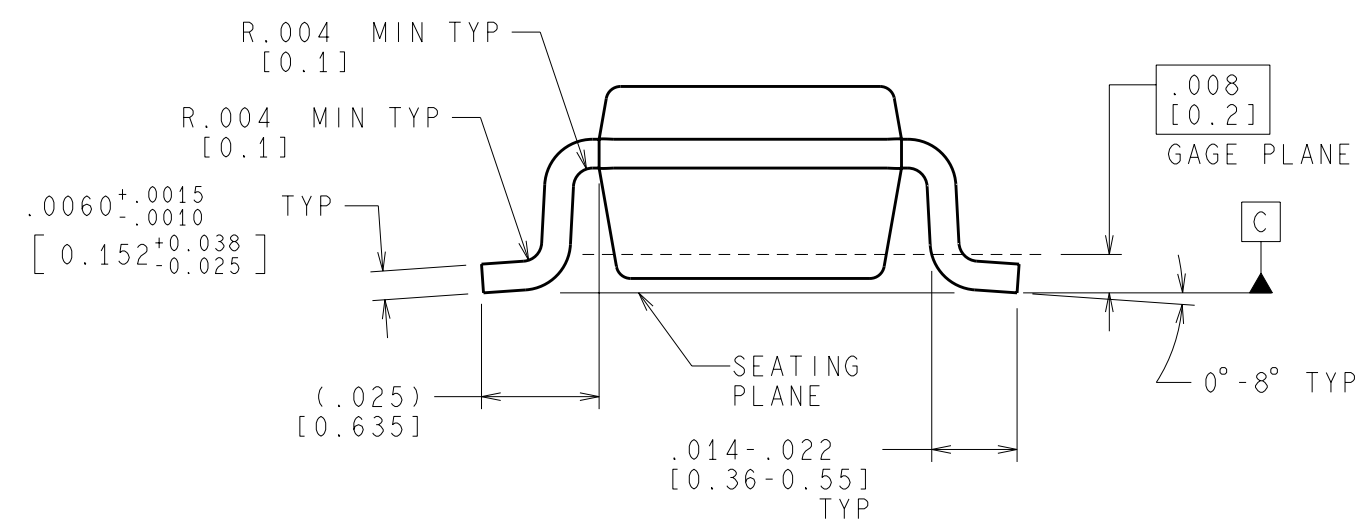
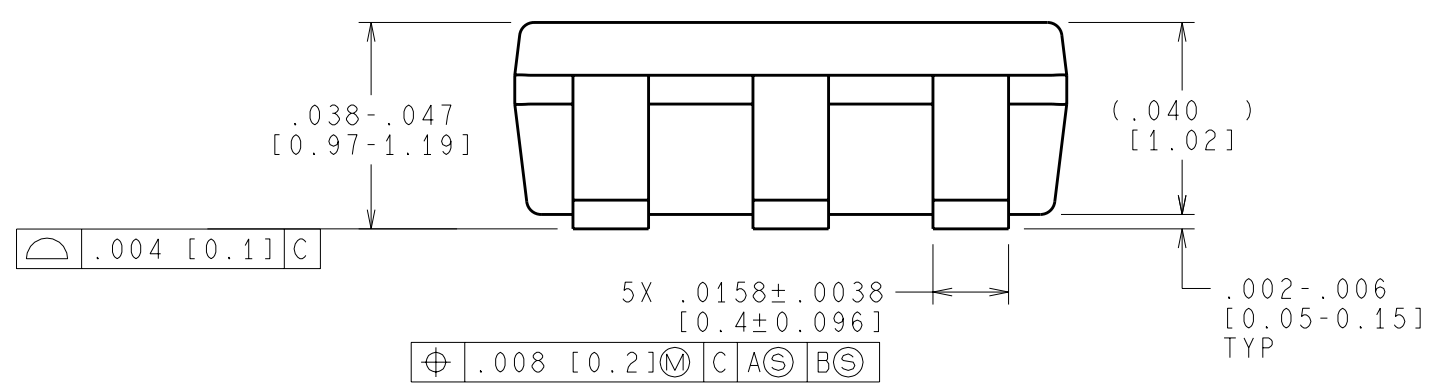


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12343	01/07/2000	TL/RW
B	REVISE NOTE 1; CHANGE DWG FORMAT TO B SIZE	983	03/27/2003	TL/RW
C	CHANGE LEAD WIDTH DIMENSION: .0158±.0038 [0.4±0.096] WAS .0170±.0025 [0.432±0.063]	1939	11/14/2005	AS/TL/AS
D	CHANGE PKG THICKNESS DIMENSION: .038-.047 [0.97-1.19] WAS .038-.048 [0.97-1.22]	2581	08/29/2008	TKYTL/TKY



LAND PATTERN RECOMMENDATION



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS
 DIMENSIONS IN () FOR REFERENCE ONLY

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MO-178, VARIATION AA.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	01/07/2000		
DFTG. CHK.	THANH LEQUANG	08/29/2008	MOLDED SOT-23, .115x.063x.040 in BODY, 5 LD, .0375 in PITCH	
ENGR. CHK.	TK Y/I	08/29/2008		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-MF05A	D
FORMERLY: N/A			SHEET 1 of 1	